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Art Unit: 2831 Examiner: Anton B. Harris
IBM Docket: AUS920031049US1(4037)

1-32 (Cancelled)

33. (New) An enclosure for an electronic device, the enclosure comprising:
an interior surface and an outside surface of the enclosure, the interior surface enclosing the electronic device;
mounting sites to mount integrated circuits, wherein the mounting sites couple with the interior surface;
a pattern of interconnects coupled with the interior surface and interconnected with the mounting sites to transmit signals between the integrated circuits; and
at least one switch coupled with the pattern of interconnects at the interior surface and exposed via the outside surface of the enclosure to receive input from outside of the enclosure.
34. (New) The enclosure of claim 33, further comprising other components coupled with the pattern of interconnects via the mounting sites.
35. (New) The enclosure of claim 34, wherein the at least one switch comprises an optical switch to toggle in response to a change in light sensed by the optical switch.
36. (New) The enclosure of claim 34, wherein the at least one switch comprises a pressure-sensitive switch coupled with the pattern of interconnects via one of the mounts.
37. (New) The enclosure of claim 33, wherein the pattern of interconnects comprises a conductive paint applied directly to the enclosure, wherein the enclosure is composed of a substantially non-conductive plastic.
38. (New) The enclosure of claim 37, wherein the enclosure is composed of a pliable material.

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39. (New) The enclosure of claim 33, wherein the pattern of interconnects is coupled with the enclosure via at least one layer of non-conductive laminates.
40. (New) The enclosure of claim 33, wherein the pattern of interconnects applied to an interior surface of the enclosure comprises a layer of metal having portions etched away to reveal the pattern of interconnects.
41. (New) A system comprising:
an enclosure comprising an interior surface and an outside surface, the interior surface enclosing an electronic device;
integrated circuits;
mounts in the enclosure to mount the integrated circuits, wherein the mounts couple with the interior surface;
a pattern of interconnects coupled with the interior surface and interconnected with the mounts to transmit signals between the integrated circuits; and
at least one switch coupled with the pattern of interconnects and exposed via the outside surface of the enclosure to receive input from outside of the system.
42. (New) The system of claim 41, further comprising sensors to sense environmental conditions, the sensors being oriented to face the exterior of the enclosure.
43. (New) The system of claim 41, wherein the pattern of interconnects resides on a laminate, the laminate being adhered to the interior surface of the enclosure.
44. (New) The system of claim 41, wherein the pattern of interconnects is coupled with a circuit board internal of the enclosure to communicatively couple the integrated circuits with other components mounted to the circuit board.
45. (New) A method comprising:
transmitting signals via interconnects;

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transmitting the signals on an interior surface of an enclosure based upon a pattern of the interconnects on the interior surface, wherein the enclosure comprises the interior surface and an outside surface, the interior surface enclosing an electronic device, to one or more mounting sites on the interior surface,

transmitting the signals via the one or more mounting sites on the interior surface to one or more integrated circuits at the one or more mounting sites; and

receiving input from outside of the enclosure based upon a change in state of a switch exposed to the outside via an outside surface of the enclosure, to the interconnects at the interior surface of the enclosure.

46. (New) The method of claim 45, further comprising coupling the at least one component to the interior surface at one of the mounting sites to mount the at least one component to the hardware casing.
47. (New) The method of claim 46, wherein coupling the at least one component comprises mounting a sensor to the hardware casing to couple the sensor with the interconnects.
48. (New) The method of claim 47, wherein mounting the sensor comprises mounting the sensor to the interior surface of the hardware casing to sense environmental conditions via the hardware casing.
49. (New) The method of claim 46, wherein coupling the at least one component to the interior surface comprises coupling the at least one component to the hardware casing to dissipate heat generated by the at least one component via the hardware casing.
50. (New) The method of claim 46, wherein coupling the at least one component to the interior surface comprises coupling the at least one component with a heat sink incorporated into the hardware casing to conduct heat from the at least one component to an environment outside the hardware casing.

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51. (New) The method of claim 45, wherein transmitting signals via the interconnects comprises applying one of the signals to one of the interconnects to conduct the one of the signals via a metal line of the interconnects to at least one of the one or more integrated circuits.
52. (New) The method of claim 51, wherein receiving comprises conductively interconnecting the metal line with the at least one of the one or more integrated circuits at the one or more mounting sites.